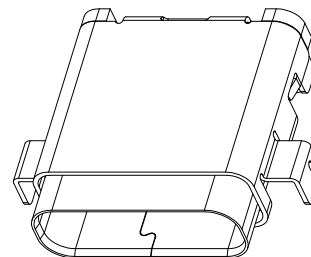
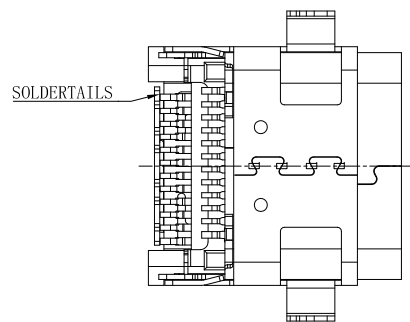
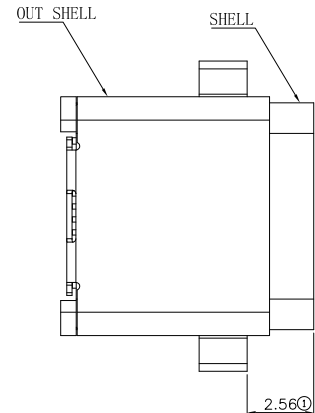


GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2015/01/23	Phebe Su
A1			Add RATINGS	2015/06/22	Phebe Su
A2			Add tags	2016/05/09	Phebe Su



NOTES:

1. MATERIAL:

HOUSING: THERMOPLASTIC, UL94V-0, COLOR:BLACK

CONTACT: COPPER ALLOY

SHELL: STAINLESS STEEL

GUARD: STAINLESS STEEL

SPRING: STAINLESS STEEL

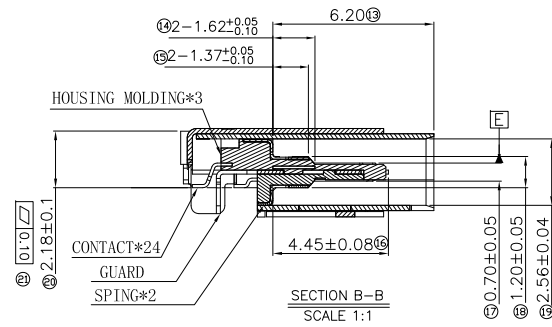
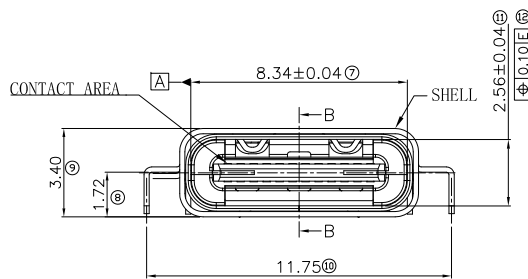
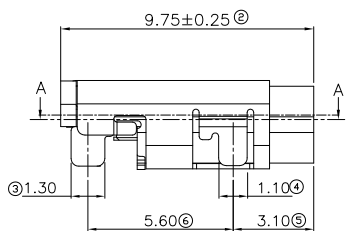
2. Finish:

CONTACT: GOLD FLASH PLATING ON CONTACT AREA

GOLD FLASH PLATING ON SOLDER TAILS

80u"Min Ni UNDERPLATING OVER ALL

SHELL: 50u"Min Ni PLATING OVER ALL.



2. PRODUCT SPECIFICATION:

VOLATAGE RATING: 100V AC

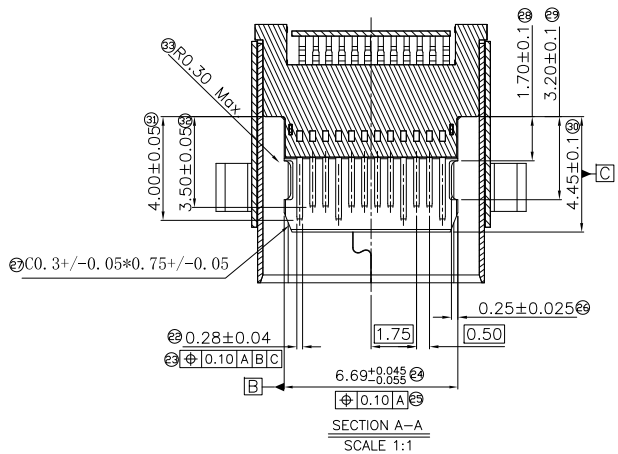
INSULATION RESISTANCE: 100MΩ

CONTACT RESISTANCE: 40mΩ

INSERT FORCE: 5-20N Max.

EXTRACT FORCE: 8-20N Min.

DURABILITY: 10000 CYSLES




MATRIX PART NO:

MATRIX USB MUSB 12 - 01 - 98

Pin Number

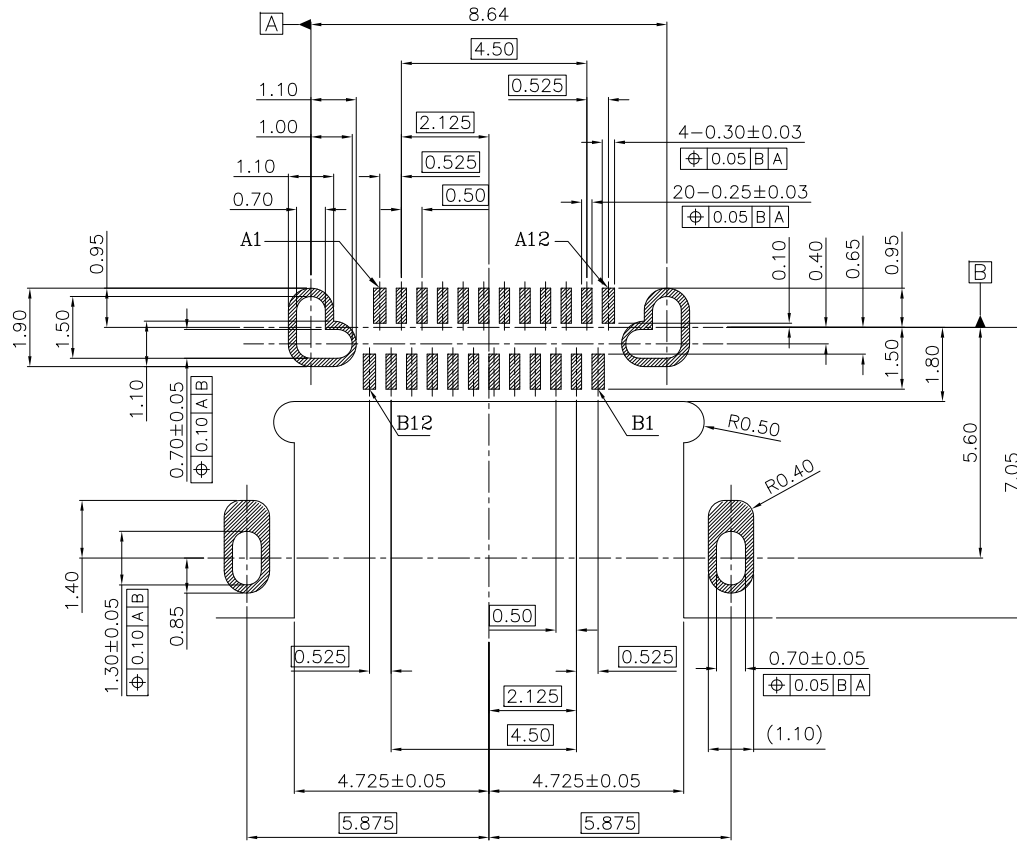
Series number

Plating
01: Gold Flash
15: 15u"
30: 30u"

NO	VARIETY	QTY	METERIAL	REMARK
 Matrix Electronics Co.,Ltd				
TOLERANCE: X.X ±0.25 X.XX ±0.20 X.XXX ±0.10 ANGLE: ±3°		DESIGN BY : Phebe Su	DATE : 2016/05/09	PART NAME: USB 3.1 TYPE C Gen 2 Female R/A, Offset Type, CL 0.02
APPROVED BY1: Richard Hsieh		DATE : 2016/05/09	PART NO.	MUSB12-01-98
APPROVED BY2: Richard Hsieh		DATE : 2016/05/09	MOLD NO.	NA
UNIT: mm [inch] SCALE: 1:1 SIZE: A4		DATE : 2016/05/09	DRAW NO.	
			SHEET NO.	1 OF 2

GP Component



REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2015/01/23	Phebe Su
A1			Add RATINGS	2015/06/22	Phebe Su
A2			Add tags	2016/05/09	Phebe Su



RECOMMEND PCB LAYOUT
(THICKNESS: 1.00 OR 1.20mm)

USB TYPE-C FULL-FEATURED RECEPTACLE INTERFACE PIN ASSIGNMENTS

PIN	Signal Name	Description	PIN	Signal Name	Description
A1	GND	Ground return	B12	GND	Ground return
A2	SSTXp1	Positive half of first SuperSpeed TX differential pair	B11	SSTXp1	Positive half of first SuperSpeed TX differential pair
A3	SSTXn1	Negative half of first SuperSpeed TX differential pair	B10	SSTXn1	Negative half of first SuperSpeed TX differential pair
A4	VBUS	Bus Power	B9	VBUS	Bus Power
A5	CC1	Configuration Channel	B8	CC1	Configuration Channel
A6	Dp1	Positive half of the USB 2.0 differential pair-Position 1	B7	Dp1	Positive half of the USB 2.0 differential pair-Position 1
A7	Dn1	Negative half of the USB 2.0 differential pair-Position 1	B6	Dn1	Negative half of the USB 2.0 differential pair-Position 1
A8	RFU1	Reserved for Future Use (RFU)	B5	RFU1	Reserved for Future Use (RFU)
A9	VBUS	Bus Power	B4	VBUS	Bus Power
A10	SSRXn2	Negative half of second SuperSpeed RX differential pair	B3	SSRXn2	Negative half of second SuperSpeed RX differential pair
A11	SSRXp2	Positive half of second SuperSpeed RX differential pair	B2	SSRXp2	Positive half of second SuperSpeed RX differential pair
A12	GND	Ground return	B1	GND	Ground return

NO	VARIETY	QTY	MATERIAL	REMARK
 Matrix Electronics Co.,Ltd				
TOLERANCE: X.X ±0.25 X.XX ±0.20 X.XXX ±0.10 ANGLE: ±3°		DESIGN BY : Phebe Su	DATE : 2016/05/09	PART NAME: USB 3.1 TYPE C Gen 2 Female R/A_Offset Type, CL 0.02
 UNIT: mm [inch]		CHECKED BY: Vicky Hsieh	DATE : 2016/05/09	PART NO. MUSB12-01-98
SCALE: 1:1 SIZE: A4		APPROVED BY1: Richard Hsieh	DATE : 2016/05/09	MOLD NO. NA
		APPROVED BY2: Richard Hsieh	DATE : 2016/05/09	DRAW NO. SHEET NO. 2 OF 2